

AREA OF INTEREST

Papers in the following areas are invited by the symposium, but papers in other related areas will also be considered:

- Abrasive machining
- Abrasive jet machining
- Advanced cutting technology
- Beam processing and related topics
- CMP and semiconductor wafer processing
- Applications of abrasive technologies
- Eco-machining
- EDM and non-traditional machining
- Ultrasonic machining
- Finishing, lapping, polishing, and deburring
- Die, mold and related topics
- Grinding wheel and abrasive grain technologies
- High-speed and high-efficiency machining
- In-process measurement, monitoring, and metrology
- Machine tools and systems, tooling
- Additive manufacturing and related topics
- Micro/nano-machining
- Surface integrity and materials characterization
- Tribology in manufacturing
- Truing, dressing and ELID

IMPORTANT DATES *Extended

March 1	Full paper submission to both IJAT and ISAAT (Closed)
May 28*	Abstract submission to ISAAT (Closed)
Jul. 16*	Full paper submission to ISAAT (Closed)
Sep. 15*	Notification of ISAAT paper acceptance
Sep. 30*	Submission of final ISAAT paper
Oct. 31*	Payment of early registration fee
Nov. 30	Conference registration and reception
Dec.1-2	Technical sessions
Dec. 3	Technical visit

SUBMISSION GUIDELINE

- Authors will be provided the options to submit their papers to ISAAT proceedings only, or to both ISAAT proceedings and the International Journal of Abrasive Technology (IJAT, EI indexed).
- Abstract submission to ISAAT: The abstract must include paper title, authors and their affiliations, and a summary of the paper within 200 words.
- Full ISAAT papers must be written in English of length from 4 to 6 proceedings pages. The version of the paper submitted to the IJAT has no limit on the number of pages. **The committee has decided to allow a one-page abstract for this time only.**
- Each paper must be formatted and submitted according to the Instructions for Authors available in the conference website.

EXCELLENT PAPER

ISAAT Excellent Paper Awards will be selected for 10 presentations. Details will be available on the ICAT website.

PAPER PRESENTATION & PUBLICATION

All papers will be peer reviewed. Accepted papers MUST be presented in oral or poster session. Each delegate may present up to two papers (a publication fee will be charged for the second paper).

ACCOMMODATION

Information of hotel will be available on the conference website.

TRAVEL INFORMATION

Travel information will be available on the conference website.

SYMPOSIUM SECRETARIAT

Prof. Jun Shimizu Email: isaat2021@gmail.com

For conference details, updates and downloadable documents, visit the conference website at:

<http://www.scoop-japan.com/kaigi/isaat2021/>



1st Circular (Ver. 3)

Call for Papers

ISAAT 2021

The 23rd International Symposium on
Advances in Abrasive Technology
30 Nov. – 3 Dec. 2021
Niseko, Hokkaido, Japan



Organized by

The Japan Society for Abrasive Technology (JSAT)
International Committee for Abrasive Technology (ICAT)



Sponsored by

The Japan Society for Abrasive Technology (JSAT)
Machine Tool Engineering Foundation
The Precise Measurement Technology Promotion Foundation
Mazak Foundation
NSK Foundation for the Advancement of Mechatronics
(The sponsors are collecting continuously)

Supported by

The Japan Society for Precision Engineering (JSPE)

HISTORY & SCOPE

The International Symposium on Advances in Abrasive Technology (ISAAT) was first held in Sydney, Australia in 1997. Since 2002, JSAT and ICAT have been jointly organizing this exciting annual event for this community and the symposia have been successfully held in Hong Kong, China, UK, Turkey, Russia, US, Japan, Australia, Taiwan, China, Germany, Singapore, China, Republic of Korea, Sweden and Canada. An emphasis of the ISAAT series is to bring together both academic researchers and industrial practitioners from around the world for the interchange of the latest developments and applications in abrasive technologies. The ISAAT2021 in Niseko, Hokkaido, Japan will continue to promote the discipline development and research collaboration, and to foster the growth of young engineers and researchers in this field.

REGISTRATION (On-site or Online Attendance)

Full registration (On-site)	JPY 70,000 (by Oct.31, 2021)
Student registration (On-site)	JPY 50,000 (by Oct.31, 2021)
Late registration (On-site)	JPY 80,000 (Full registration)
After Nov. 1, 2021	JPY 60,000 (Student registration)
General registration (Online)	JPY 40,000 (by Oct.31, 2021)
Student registration (Online)	JPY 30,000 (by Oct.31, 2021)
Late registration (Online)	JPY 50,000 (General)
After Nov. 1, 2021	JPY 40,000 (Student)

A full registration and a student registration cover the costs for conference proceedings, welcoming reception, banquet, morning and afternoon refreshments, attendance to all the technical sessions, and lunches.

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*At the moment, a Hybrid (On-site & Online) symposium is planned. However, depending on the global COVID'19 pandemic situation, it may be switched to full-online one. Thank you for your understanding.

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